Henkel Solutions for Leadframe Packaging
Wafer Backside Coatings

WAFFER BACKSIDE COATINGS (WBC) FOR WIREBOND LEADFRAME PACKAGING

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ELECTRICALLY CONDUCTIVE WAFFER BACKSIDE COATINGS (WBC)

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<tr>
<th>PRODUCT</th>
<th>DESCRIPTION</th>
<th>KEY ATTRIBUTES</th>
<th>DIE SIZE (mm)</th>
<th>SUBSTRATE FINISH</th>
<th>MOISTURE SENSITIVITY LEVEL, MSL</th>
<th>VOLUME RESISTIVITY (Ohm·cm)</th>
<th>THERMAL CONDUCTIVITY (W/m·K)</th>
<th>RECOMMENDED CURE</th>
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| LOCTITE ABLESTIK 8008 | Ag-filled die attach wafer backside coating adhesive | • Excellent stencil printing and low surface roughness  
• Void-free bondline without bleed  
• Oven B-stage and snap or oven cure | ≤ 3 x 3 | Cu, Ag or PPF | LI 260°C capable | 1.0 x 10⁴ | 2.2 | 60 sec. at 230°C (snap) |
| LOCTITE ABLESTIK 8008HT | Ag-filled die attach wafer backside coating adhesive | • Applied by stencil printing  
• Void-free bondline without bleed  
• Oven B-stage and snap or oven cure | ≤ 1 x 1 | Cu, Ag or PPF | LI 260°C capable | 6.0 x 10⁴ | 11.0 | 20 sec. at 170°C (snap) |
| LOCTITE ABLESTIK 8008MD | Ag-filled die attach wafer backside coating adhesive | • Applied by stencil printing  
• Low stress  
• Good substrate wetting  
• Oven B-stage and oven cure | ≤ 4 x 4 | Cu, Ag or PPF | LI 260°C capable | 5.0 x 10⁴ | 6.0 | 10 min. ramp and 60 min. hold at 115°C |

ELECTRICALLY NON-CONDUCTIVE WAFFER BACKSIDE COATINGS (WBC)

<table>
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<tr>
<th>PRODUCT</th>
<th>DESCRIPTION</th>
<th>KEY ATTRIBUTES</th>
<th>DIE SIZE (mm)</th>
<th>SUBSTRATE FINISH</th>
<th>MOISTURE SENSITIVITY LEVEL, MSL</th>
<th>MODULUS AT 25°C (MPa)</th>
<th>CTE (ppm/°C) Below T_g Above T_g</th>
<th>RECOMMENDED CURE</th>
</tr>
</thead>
</table>
| LOCTITE ABLESTIK 8008NS | Alumina/silica-filled, epoxy die attach wafer backside coating adhesive | • Applied by stencil or screen printing  
• Consistent bondline down to 25 µm with minimal die tilt  
• Oven B-stage and oven cure | ≤ 4 x 4 | Cu, Ag or PPF | LI 260°C capable | 4,376 | 33 | 136 | 2 hr. at 160°C |
| LOCTITE ABLESTIK WBC 8901UV | Die attach wafer backside coating adhesive | • Wide process windows  
• ≤ 5 to 60 µm bondline control  
• Low viscosity before B-stage  
• Can be spray coated on Dicing Before Grinding (DBG) wafers  
• UV B-stage and oven cure | ≤ 1 x 1 | Cu, Ag or PPF | LI 260°C capable | 3,585 | 45 | 142 | 15 min. ramp and 30 min. hold at 90°C + 4 min. ramp and 45 min. hold at 120°C |

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